



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

ATTY.'S DOCKET: 98 P7501 US 01

In re the application of:
Ramachandran et al.

Group Art: 1746

Serial No.: 09/204,706

Examiner: A. Olsen

Filing Date: December 3, 1998

Title: REMOVAL OF POST-RIE POLYMER)
ON Al/Cu METAL LINE)

AMENDMENT UNDER 37 C.F.R. §1.116

Honorable Commissioner of Patents and Trademarks
Washington, D.C. 20231

Sir:

In reply to the Office Action mailed Jun 27, 2001, which rejected the claims in the above-identified patent application, applicants respectfully request reconsideration, based upon the amendments hereinafter set forth

IN THE CLAIMS:

13. (Twice Amended) In a metal etch tool for removing post-RIE polymer rails formed on a Al/Cu metal line of a semiconductor structure, the improvement comprising an integrated metal etch tool comprising therein: [separate] strip chamber means [for

forming a water-only plasma process] to strip the photo-resist layer of a semiconductor composite structure with water only plasma subsequent [previously subjected] to a RIE

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